

## ABSTRACT OF THE DISCLOSURE

5 The present invention is for a thermally controlled package for oscillators, particularly  
evacuated miniature surface acoustical wave oscillators (EMSO) devices. In a preferred  
embodiment the surface acoustical wave device is bonded directly to a heated substrate. The  
package is evacuated to improve temperature characteristics. A temperature heater, sensor, and  
control controller are utilized to maintain the internal package temperature above ambient. In  
one embodiment there is an additional substrate layer that house components that are not  
10 sensitive to temperature with interconnects electrically connecting the heated substrate and the  
additional substrates.

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